| © Copyright 2005. IPC, Ba                         | Material Composition Declaration<br>© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both<br>international and Pan-American copyright conventions. |  |                  |   | This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility. |                |                        |                                 |                     |                  |           |  |
|---|---|--|------------------|---|---|----------------|------------------------|---------------------------------|---------------------|------------------|-----------|--|
|   | 21.1 IPC Web Site for Information on IPC-1752 Standard Form T<br>http://www.ipc.org/IPC-175x Distribution   |  |                  | * Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materials and |   |                |                        | als and Mf                      | and Mfg Information |                  |           |  |
| Supplier Information                              |   |  |                  |   |   |                |                        |                                 |                     |                  |           |  |
| Company name* Company unique ID                   |   |  |                  | Unique ID Authority   |   |                | Response Date*         |                                 |                     |                  |           |  |
| nsemi   |   |  |                  |   |   |                |                        |                                 | 2023-06-06          |                  |           |  |
| Contact Name                                      | tact Name Title - Contact   |  |                  | Р   | Phone - Contact*  |                |                        |                                 | Email - Contact*    |                  |           |  |
| roduct-Env-Stewards Product Enviro Compliance     |   |  |                  | NA  |   |                |                        | Product-Env-Stewards@onsemi.com |                     |                  |           |  |
| Authorized Representative* Title - Representative |   |  |                  | Phone - Representative*   |   |                |                        | Email - Representative*         |                     |                  |           |  |
| Product-Env-Stewards Product Enviro Compliance    |   |  |                  | NA  |   |                |                        | Product-Env-Stewards@onsemi.com |                     |                  |           |  |
| Requester Item Number M                           | Mfr Item Number Mfr Item N  |  | tem Name         |   | Effective Date  | Version        | Manufacturing Site     | v                               | /eight*             | UOM              | Unit Type |  |
| TI  | LV431CSN1T1G  | CSN1T1G Low Voltage Precision<br>Regulator |                  | int 2   | 2023-06-06  |                | MY1                    |                                 | .14                 | mg               | Each      |  |
| Manufacturing Proccess Information                |   |  |                  |   |   |                |                        |                                 |                     |                  |           |  |
| Terminal Plating / Grid Array Material            | Ferminal Plating / Grid Array Material Terminal Base Alloy J-S  |  | STD-020 MSL Rati | ing   | Peak Proce  | ss Body Temper | ature Max Time at Peak | Temperatu                       | re Numbe            | er of Reflow Cyc | les       |  |
| Matte Tin (Sn) - annealed CU Alloy 1              |   |  |                  | 260   | С   | 30             | second                 | ls <b>3</b>                     |                     |                  |           |  |
| Comments  |   |  |                  |   |   |                |                        |                                 |                     |                  |           |  |
| level 1 - maximum time at peak temperature dur    | ing soldering is 10-3   | 0 seconds                                  |                  |   |   |                |                        |                                 |                     |                  |           |  |
| For more information regarding material compo     | sition please refer to  | page 3                                     |                  |   |   |                |                        |                                 |                     |                  |           |  |

| RoHS Material Composition Declaration  |  |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |
|--|--|--|---|---|---|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl bhthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>y others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the   | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and co<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa  | ances per the definitio  | on above  | Supplier Acceptance                             | * Accepted  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per   | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU   |  |   |   |   |  |  |  |  |  |
| Declaration Signature  |  |  |   |   |   |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester  | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska  | Le   |   |   |   |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance  | CAS              | Exempt | Weight | Unit of Measure |
|----------------------|--------|-----------------|----------|--|------------------|--------|--------|-----------------|
| Die                  | 0.16   | mg              | Supplier | Silicon (Si)   | 7440-21-3        |        | 0.16   | mg              |
| Die Attach           | 0.18   | mg              |          | Epoxy resin  | proprietary data |        | 0.054  | mg              |
|                      |        |                 | Supplier | Fatty acids, C18-unsatd., dimers, polymers with epichlorhydrin         | 68475-94-5       |        | 0.054  | mg              |
|                      |        |                 | Supplier | 2,2'-[[2-(oxiranylmethoxy)-1,3-<br>phenylene]bis(methylene)]bisoxirane | 13561-08-5       |        | 0.054  | mg              |
|                      |        |                 | Supplier | 4-Methyl-2-Phenyl-1H-Imidazole   | 827-43-0         |        | 0.0162 | mg              |
|                      |        |                 | Supplier | Phenolic Resin (Novolac)   | 9003-35-4        |        | 0.0018 | mg              |
| Lead Frame           | 2.75   | mg              | Supplier | Silver (Ag)  | 7440-22-4        |        | 0.4895 | mg              |
|                      |        |                 | В        | Nickel (Ni)  | 7440-02-0        |        | 0.8497 | mg              |
|                      |        |                 | Supplier | Iron (Fe)  | 7439-89-6        |        | 1.1743 | mg              |
|                      |        |                 | Supplier | Copper (Cu)  | 7440-50-8        |        | 0.2365 | mg              |
| Mold Compound-Black  | 4.9    | mg              |          | Epoxy resin  | proprietary data |        | 0.245  | mg              |
|                      |        |                 | Supplier | Phenolic Resin   | Proprietary Data |        | 0.245  | mg              |
|                      |        |                 | Supplier | Ortho Cresol Novolac Resin   | 29690-82-2       |        | 0.098  | mg              |
|                      |        |                 | Supplier | Carbon Black (C)   | 1333-86-4        |        | 0.0245 | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2)  | 60676-86-0       |        | 4.2875 | mg              |
| Plating              | 0.14   | mg              | Supplier | Tin (Sn)   | 7440-31-5        |        | 0.14   | mg              |
| Wire Bond - Au       | 0.01   | mg              | Supplier | Gold (Au)  | 7440-57-5        |        | 0.01   | mg              |

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).